

# Schottky Barrier Diode, 500 mA, 30 V

## NSR05T304MX

These Schottky barrier diodes are optimized for low forward voltage drop and low leakage current that offers the most optimal power dissipation in applications. They are housed in spacing saving micro-packaging ideal for space constraint applications.

### Features

- Low Forward Voltage Drop – 410 mV (Typ.) @  $I_F = 500$  mA
- Low Reverse Current – 35  $\mu$ A (Typ.) @  $V_R = 30$  V
- 500 mA of Continuous Forward Current
- High Switching Speed
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

### Typical Applications

- LCD and Keypad Backlighting
- Camera Photo Flash
- Buck and Boost dc-dc Converters
- Reverse Voltage and Current Protection
- Clamping & Protection

### MAXIMUM RATINGS

| Rating                                                                    | Symbol    | Value | Unit |
|---------------------------------------------------------------------------|-----------|-------|------|
| Reverse Voltage                                                           | $V_R$     | 30    | V    |
| Forward Current (DC)                                                      | $I_F$     | 500   | mA   |
| Forward Surge Current<br>(60 Hz @ 1 cycle)                                | $I_{FSM}$ | 2.2   | A    |
| Repetitive Peak Forward Current<br>(Pulse Wave = 1 sec, Duty Cycle = 66%) | $I_{FRM}$ | 1.4   | A    |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.



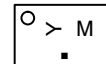
**ON Semiconductor®**

[www.onsemi.com](http://www.onsemi.com)



**X2DFN2  
CASE 714AB**

### MARKING DIAGRAM



- Y = Specific Device Code  
M = Date Code  
■ = Pb-Free Package



### ORDERING INFORMATION

| Device         | Package             | Shipping†                         |
|----------------|---------------------|-----------------------------------|
| NSR05T304MXT5G | X2DFN2<br>(Pb-Free) | 2 mm Pitch<br>8000/Tape &<br>Reel |

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

# NSR05T304MX

## THERMAL CHARACTERISTICS

| Characteristic                                                                                           | Symbol                   | Min        | Typ | Max         | Unit                     |
|----------------------------------------------------------------------------------------------------------|--------------------------|------------|-----|-------------|--------------------------|
| Thermal Resistance<br>Junction-to-Ambient (Note 1)<br>Total Power Dissipation @ $T_A = 25^\circ\text{C}$ | $R_{\theta JA}$<br>$P_D$ |            |     | 310<br>480  | $^\circ\text{C/W}$<br>mW |
| Thermal Resistance<br>Junction-to-Ambient (Note 2)<br>Total Power Dissipation @ $T_A = 25^\circ\text{C}$ | $R_{\theta JA}$<br>$P_D$ |            |     | 150<br>1000 | $^\circ\text{C/W}$<br>mW |
| Junction and Storage Temperature Range                                                                   | $T_J, T_{stg}$           | -55 to +85 |     |             | $^\circ\text{C}$         |

1. Mounted onto a 4 in square FR-4 board 50 mm sq. 1 oz. Cu 0.06" thick single sided. Operating to steady state.
2. Mounted onto a 4 in square FR-4 board 650 mm sq. 1 oz. Cu 0.06" thick single sided. Operating to steady state.

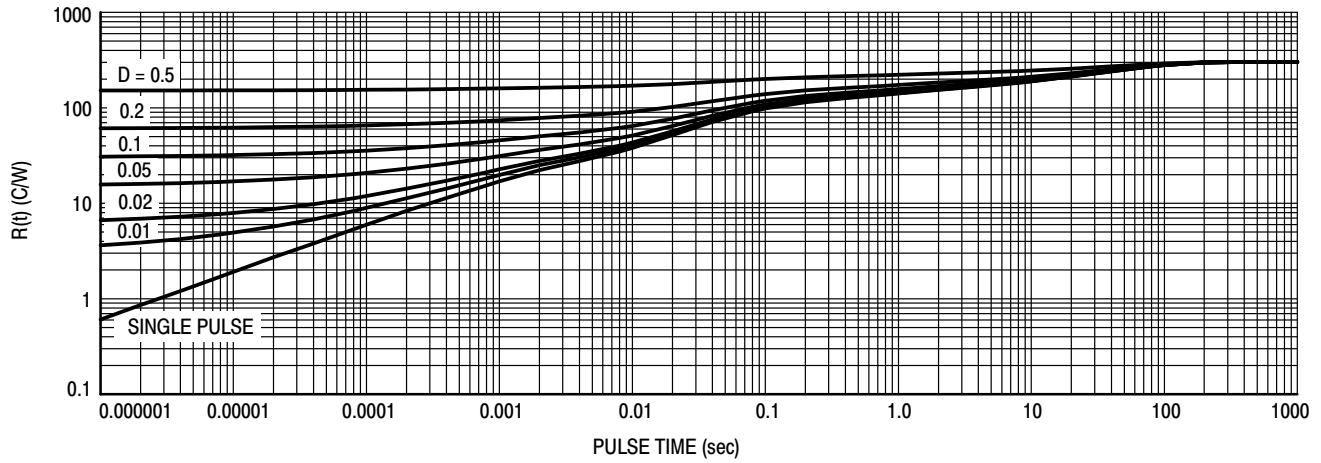


Figure 1. Thermal Response (Note 1)

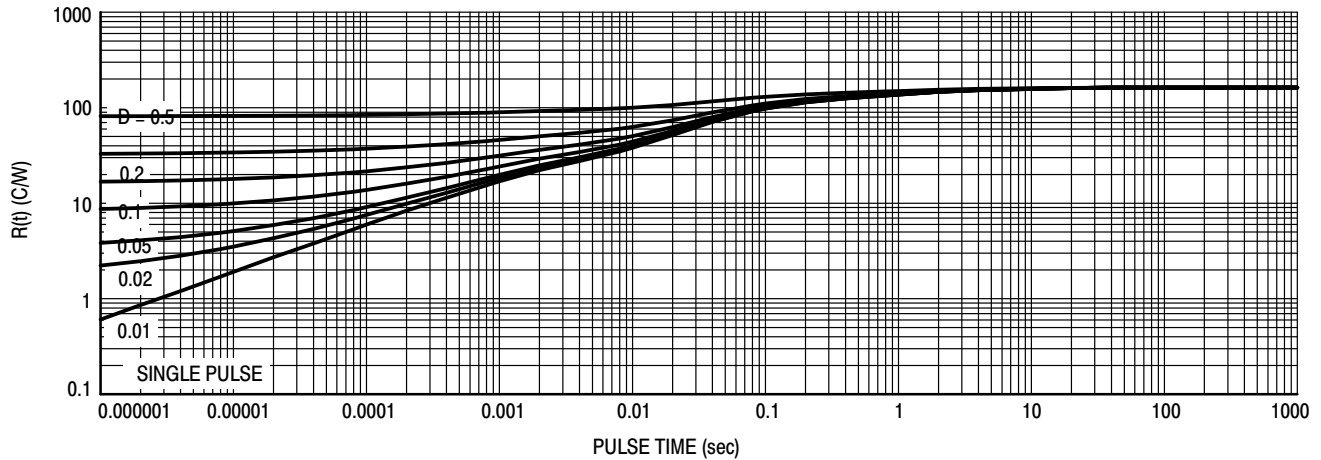
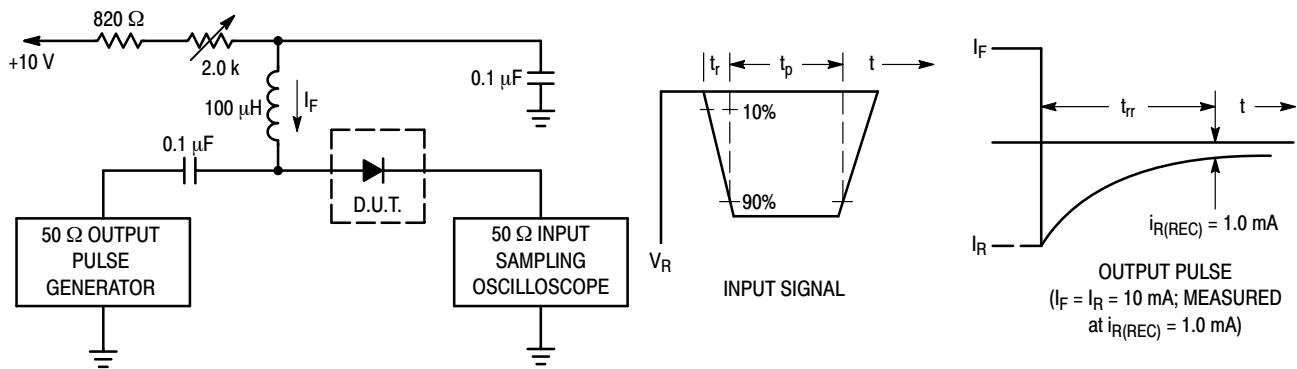


Figure 2. Thermal Response (Note 2)

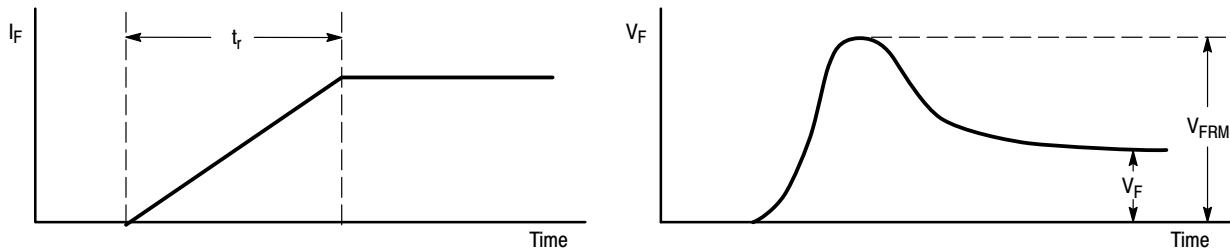
# NSR05T304MX

## ELECTRICAL CHARACTERISTICS (T<sub>A</sub> = 25°C unless otherwise noted)

| Characteristic                                                                                                                     | Symbol           | Min | Typ                      | Max                      | Unit |
|------------------------------------------------------------------------------------------------------------------------------------|------------------|-----|--------------------------|--------------------------|------|
| Reverse Leakage<br>(V <sub>R</sub> = 10 V)<br>(V <sub>R</sub> = 30 V)                                                              | I <sub>R</sub>   |     | 20<br>35                 | 50<br>75                 | μA   |
| Forward Voltage<br>(I <sub>F</sub> = 10 mA)<br>(I <sub>F</sub> = 100 mA)<br>(I <sub>F</sub> = 200 mA)<br>(I <sub>F</sub> = 500 mA) | V <sub>F</sub>   |     | 215<br>295<br>330<br>410 | 245<br>320<br>355<br>435 | mV   |
| Total Capacitance<br>(V <sub>R</sub> = 1.0 V, f = 1.0 MHz)                                                                         | C <sub>T</sub>   |     | 30                       |                          | pF   |
| Reverse Recovery Time<br>(I <sub>F</sub> = I <sub>R</sub> = 10 mA, I <sub>R(REC)</sub> = 1.0 mA, Figure 3)                         | t <sub>rr</sub>  |     | 15                       |                          | ns   |
| Peak Forward Recovery Voltage<br>(I <sub>F</sub> = 100 mA, t <sub>r</sub> = 20 ns, Figure 4)                                       | V <sub>FRM</sub> |     | 430                      |                          | mV   |



**Figure 3. Recovery Time Equivalent Test Circuit**



**Figure 4. Peak Forward Recovery Voltage Definition**

TYPICAL CHARACTERISTICS

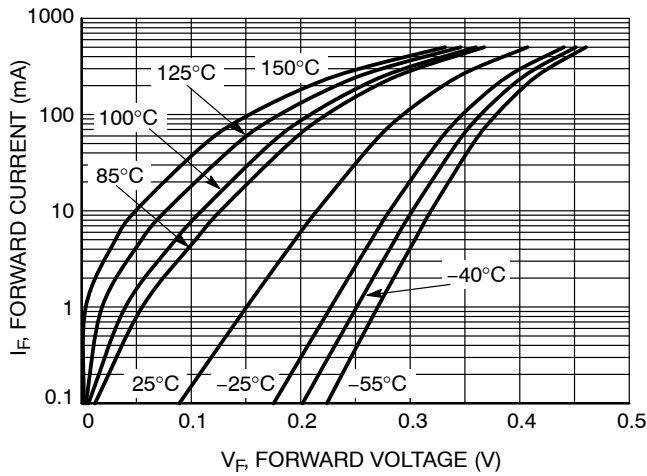


Figure 5. Forward Voltage

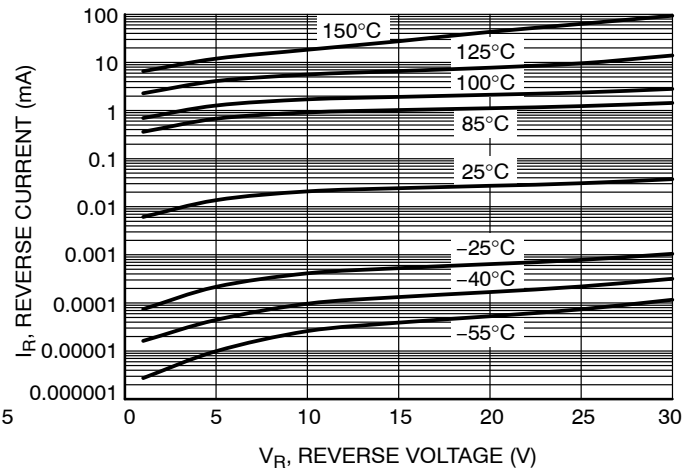


Figure 6. Leakage Current

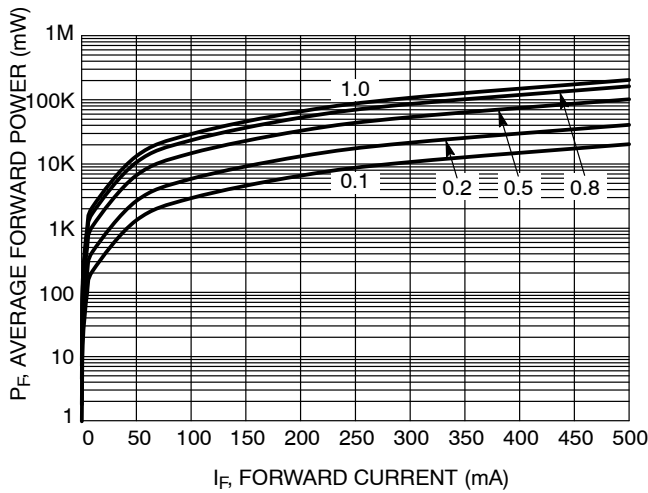


Figure 7. Average Forward Power Dissipation

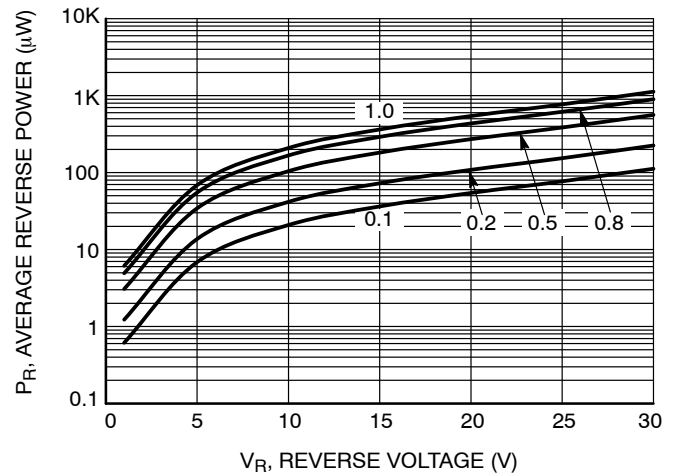


Figure 8. Average Reverse Power Dissipation

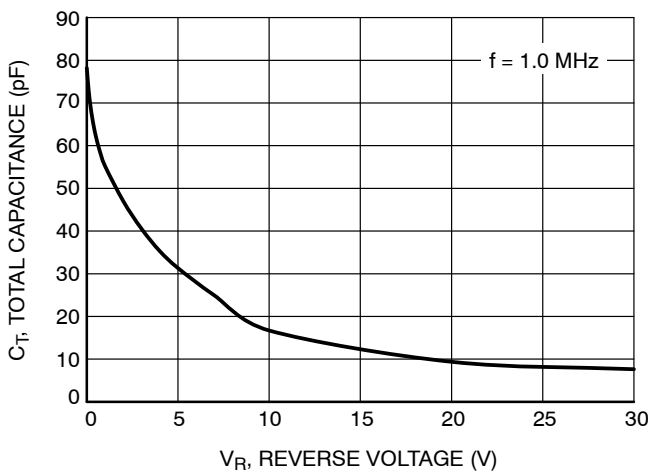


Figure 9. Total Capacitance

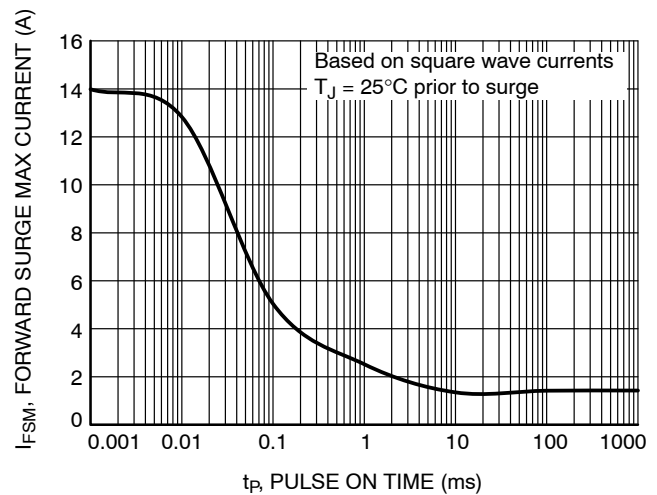
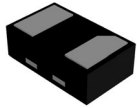
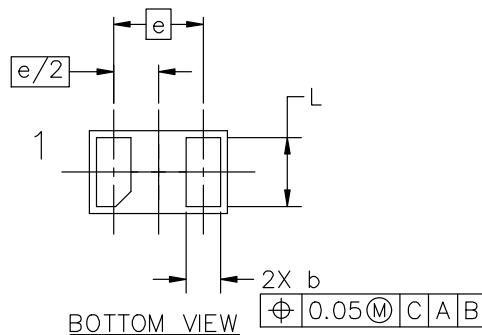
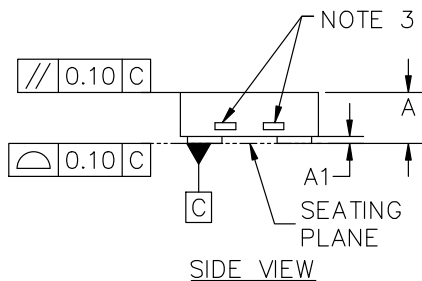
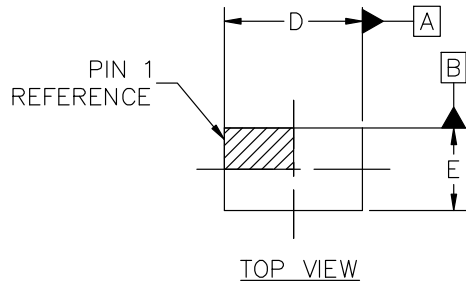


Figure 10. Forward Surge Current

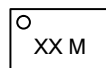


**X2DFN2 1.00x0.60x0.37, 0.65P**  
**CASE 714AB**  
**ISSUE C**

DATE 21 FEB 2024



### GENERIC MARKING DIAGRAM\*



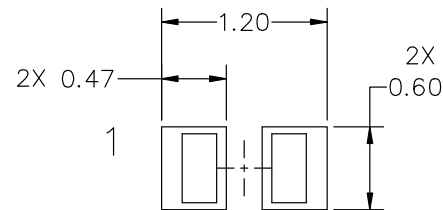
XX = Specific Device Code  
M = Date Code

\*This information is generic. Please refer to device data sheet for actual part marking.  
Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

### NOTES:

1. DIMENSIONING AND TOLERANCING CONFORM TO ASME Y14.5-2018.
2. ALL DIMENSION ARE IN MILLIMETERS.
3. EXPOSED COPPER ALLOWED AS SHOW.

| DIM | MILLIMETERS |      |       |
|-----|-------------|------|-------|
|     | MIN.        | NOM. | MAX.  |
| A   | 0.34        | 0.37 | 0.40  |
| A1  | ---         | 0.03 | 0.050 |
| b   | 0.20        | 0.25 | 0.30  |
| D   | 0.95        | 1.00 | 1.05  |
| E   | 0.55        | 0.60 | 0.65  |
| e   | 0.65 BSC    |      |       |
| L   | 0.45        | 0.50 | 0.55  |



### RECOMMENDED MOUNTING FOOTPRINT\*

\* FOR ADDITIONAL INFORMATION ON OUR Pb-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERM/D.

|                         |                                     |                                                                                                                                                                                  |
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| <b>DESCRIPTION:</b>     | <b>X2DFN2 1.00x0.60x0.37, 0.65P</b> | <b>PAGE 1 OF 1</b>                                                                                                                                                               |

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